

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16539
1.3 Title of PCN	STM32N64x and STM32N65x - product enhancement
1.4 Product Category	STM32N64x and STM32N65x
1.5 Issue date	2026-08-31

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
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2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	ST Crolles 300 (France)

4. Description of change

	Old	New
4.1 Description	Current STM32N64x and STM32N65x (Revision B) products have limitations as described in Errata Sheet ES0620 - Rev 4 - May 2025	STM32N64x and STM32N65x (New Revision X) products enhancement. New revision fixes the following limitations • System: Incorrect reset behavior when using the NRST pin. • UCPD: Rp value drift causing incorrect source current capability detection. as described in Errata Sheet ES0620 - Rev 5 - August 2026
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Functionality enhancement	

5. Reason / motivation for change

5.1 Motivation	Improvements implemented to fix bugs.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tools. Die revision changes from "B" to "X" on Package Marking
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7. Timing / schedule

7.1 Date of qualification results	2026-11-10
7.2 Intended start of delivery	2026-12-10
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16539 MDRF-GPAM RER2213 - PCN16539 STM32N6x - Die 486_X cut2.2 - Rel plan.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-08-31
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9. Attachments (additional documentations)
16539 Public product.pdf 16539 MDRF-GPAM RER2213 - PCN16539 STM32N6x - Die 486_X cut2.2 - Rel plan.pdf 16539 _Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32N645A0H3Q	
	STM32N645L0H3Q	
	STM32N645Z0H3Q	
	STM32N647A0H3Q	
	STM32N647B0H3Q	
	STM32N647I0H3Q	
	STM32N647L0H3Q	
	STM32N647X0H3Q	
	STM32N647Z0H3Q	
	STM32N655A0H3Q	
	STM32N655L0H3Q	
	STM32N655X0H3Q	
	STM32N657A0H3Q	
	STM32N657B0H3Q	
	STM32N657I0H3Q	
	STM32N657L0H3Q	
	STM32N657X0H3Q	
	STM32N657Z0H3Q	

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